

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.00437	1.24	0.06572
	Doped silicon	Silicon (Si)	7440-21-3	0.34773	98.76	5.23428
<b>Subtotal</b>				<b>0.3521</b>	<b>100</b>	<b>5.3</b>
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.01933	10.0	0.29095
	Silver alloy	Silver (Ag)	7440-22-4	0.00387	2.0	0.05819
	Lead alloy	Lead (Pb)	7439-92-1	0.17009	88.0	2.56032
<b>Subtotal</b>				<b>0.19329</b>	<b>100</b>	<b>2.90946</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.26576	100.0	4.00047
	<b>Subtotal</b>				<b>0.26576</b>	<b>100</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00976	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00651	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00976	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.03579	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	32.4761	99.81	488.8594
<b>Subtotal</b>				<b>32.53792</b>	<b>100</b>	<b>489.79001</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.3222	100.0	4.85
	<b>Subtotal</b>				<b>0.3222</b>	<b>100</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.3063	8.0	79.8752
	Filler	Silica fused	60676-86-0	53.72629	81.0	808.7364
	Metal hydroxide	Metal hydroxide		0.4643	0.7	6.98908
	Carbon Black	Carbon black	1333-86-4	0.19899	0.3	2.99532
	Polymer	Epoxy resin system		6.63288	10.0	99.844
<b>Subtotal</b>				<b>66.32876</b>	<b>100</b>	<b>998.44</b>
<b>Total</b>				<b>100.00003</b>	<b>100</b>	<b>1505.28994</b>

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